

IN THE CLAIMS:

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS:

1 1. (original): A device comprising:  
2 a tip of a bonding tool having a dissipative material for use in wire bonding  
3 machines for connecting leads to integrated circuit bonding pads, wherein the tip has a  
4 static discharge time between 0.1 and 0.5 seconds.

1 2. (original): A device comprising:  
2 a bonding tool tip having an electrically dissipative ceramic for use in capillary  
3 wedge-type wire bonding machines for connecting leads to integrated circuit bonding  
4 pads.

1 3. (original): A method of using a bonding tool tip, comprising:  
2 providing an electrically dissipative bonding tool tip;  
3 bonding a material to a device;  
4 allowing an essentially smooth current to dissipate to the device, the current  
5 being low enough so as not to damage said device being bonded and

6 high enough to avoid a build up of charge that could discharge to the device being  
7 bonded and damage the device being bonded.

1 4. (new): A device comprising:  
2 a tip having a dissipative material for use in wire bonding machines for  
3 connecting leads to integrated circuit bonding pads, wherein said dissipative material  
4 has a resistance in the range of  $5 \times 10^5$  to  $10^{12}$  ohms.

1 5. (new): The device of claim 4 wherein the range of  $5 \times 10^5$  to  $10^{12}$  ohms of the  
2 resistance is limited to  $10^5$  to  $10^{12}$  ohms.